



Materials Declaration

Package	TSSOP
Body Size	4.4
LeadCount	20
Option	Pb-Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
Byphenyl resin	9	1.46 E-03	20678
SiO2 Filler	85	1.38 E-02	195289
Phenol Resin	5	8.11 E-04	11488
Antimony_Sb2O3	0.5	8.11 E-05	1149
Brominated Resin	0.5	8.11 E-05	1149

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	96.2	3.53 E-02	499869
Ni	3	1.10 E-03	15588
Si	0.65	2.38 E-04	3377
Mg	0.15	5.50 E-05	779

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	8.44 E-04	11957

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100	2.56 E-03	36229

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	4.92 E-04	6973

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	1.36 E-02	192398

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	7.46 E-05	1057
Ag Filler	75	2.24 E-04	3170

Molding Compound

Item	PPM	Method
Pb	Not Detected	ICP AES
Cd	Not Detected	ICP AES
Hg	Not Detected	ICP AES
Cr+6	Not Detected	DIN 53314

Die Attach Paste

Item	PPM	Method
Pb	<5	ICP AES
Cd	<5	ICP AES
Hg	<5	ICP AES
Cr+6	<5	ICP AES
PBB	Not Detected	
PBDE	Not Detected	

Package Totals

Weight (g)	PPM
7.06 E-02	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability for any inaccuracy of such information.



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Leadframe

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Ni	3	1.10 E-03	15588
Si	0.65	2.38 E-04	3377
Mg	0.15	5.50 E-05	779

Internal Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Ag	100	8.44 E-04	11957

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85	2.17 E-03	30794
Pb	15	3.84 E-04	5434

Bond Wires

Item	% of Wire	Weight (g)	PPM
Au	99.99	4.92 E-04	6973

Chip

Item	% of Chip	Weight (g)	PPM
Si	100	1.36 E-02	192398

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Resin	25	7.46 E-05	1057
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Molding Compound

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